

REMARKS

No claims are amended. Thus, claims 1, 6, 14, and 15 are pending, of which claim 1 is independent.

Claim Rejections – 35 U.S.C. § 103(a)

The Office Action rejects claim 1 as allegedly unpatentable under 35 U.S.C. § 103(a) over Nakazato (U.S. Patent No. 5,071,785, hereinafter “*Nakazato*”), in view of Masaki (Japanese Patent Publication No. JP09-008124, hereinafter “*Masaki*”). The Office Action also rejects claims 6 and 15 as unpatentable over Nakazato and Masaki, further in view of Moriceau (U.S. Patent No. 6,756,285, hereinafter “*Moriceau*”).

The Office Action states that *Nakazato* does not explicitly disclose all the elements of claim 1 (Final Office Action, pg. 3). The Office Action further refers to *Masaki* for disclosure of “using a difference between the film thickness of a buried oxide film and that of an oxide film on the reverse surface being manufactured by the oxide films”.

Applicants respectfully submit that the cited documents are not properly combinable. Applicants further submit that even assuming, *arguendo*, the documents were properly combined, any combination of the documents would not arrive at Applicants’ claimed subject matter.

For example, *Nakazato* discloses bonding together two pre-warped wafers. After the two wafers are warped, the entire surfaces thereof are simply covered with oxide films at a uniform thickness for bonding. *Nakazato* does not disclose that film thicknesses are differentiated between a top and reverse surface and thus does not require the use of different thicknesses of oxide film covering the top and reverse surfaces of the wafer in order to cause warp.

Further, *Masaki* discloses bonding together two wafers, each wafer having a different oxide film thickness. However, *Masaki* further discloses the entire surfaces of each respective wafer having a uniform oxide film thickness. Thus, the wafers disclosed by *Masaki* are not warped for bonding.

Applicants respectfully note that, in the present invention, the thicknesses of the films on the top and reverse sides of a bare wafer are differentiated in order to warp the wafer (the amount of warpage being determined by the film thicknesses). Two wafers having the same warpage are subsequently fitted and bonded together, thereby achieving the bonded wafer. Applicants note that neither *Nakazaki* nor *Masaki* discloses or suggests the concept of using different thicknesses of oxide films covering the top and reverse surfaces of a wafer for warping a pre-bonded wafer; combining these documents will not arrive at Applicants' claimed subject matter.

Applicants respectfully submit that, to the extent that the rejections of claims 6 and 15 are based on the combination of *Nakazaki* and *Masaki*, further in view of *Moriceau*, these rejections are moot for at least the foregoing reasons.

Nakazaki, *Masaki*, and *Moriceau* do not singly, or in any combination, disclose or suggest using films having identical compositions being formed on the top and reverse sides thus creating warpage by differentiating film thicknesses between top and reverse sides. Applicants respectfully submit that claim 1 is patentable over the cited documents and request withdrawal of the rejection. Applicants further submit that claims 6, 14, and 15 depend from and inherit the limitations of claim 1 and are patentable for at least the same reasons.

CONCLUSION

For all the above reasons, it is respectfully submitted that all pending claims are patentable over the documents employed in the rejections of record. Applicants request reconsideration and withdrawal of the rejections of record. Allowance of the application with an early mailing date of the Notices of Allowance and Allowability is therefore respectfully requested.

If there should be any questions, the Examiner is invited to contact the undersigned at the telephone number listed below.

Respectfully Submitted,
Akihiko ENDO et al.


William S. Boshnick
Reg. No. 44550

Stephen M. Roylance
Reg. No. 31,296

December 8, 2008
GREENBLUM & BERNSTEIN, P.L.C.
1950 Roland Clarke Place
Reston, VA 20191
(703) 716-1191